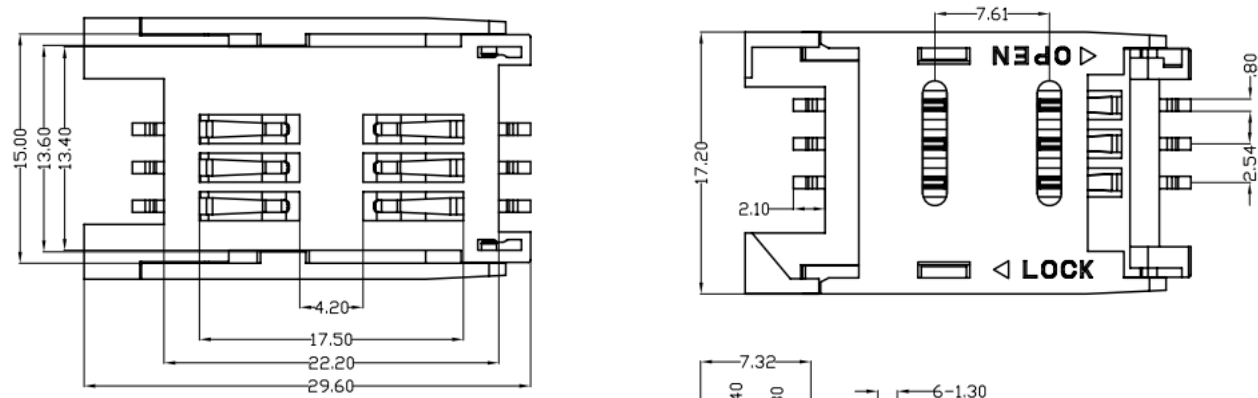


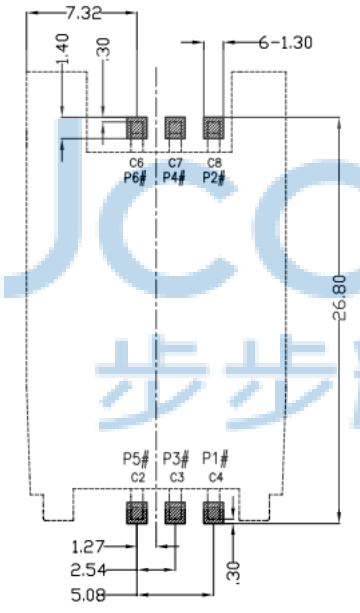
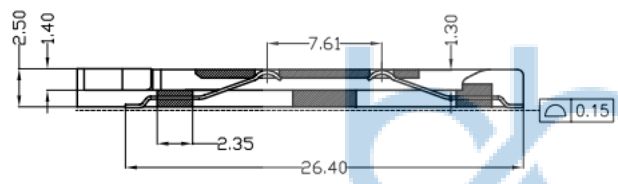
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



- A.Material:
- Insulator:High temperature thermoplastic UL94V-0,(BLACK LCP)
 - Pho.Bronze:Plating,
50U" MIN NICKEL UNDERPLATED;
3-8U" GOLD ON THE CONTACT AREA;
100U" TIN PLATING ON SOLDER TAIL

- B.Electrical specifications:
- Voltage rating: 10 V AC
 - Current rating: 0.5A
 - Dielectric strength: 500V AC for 1 minute min
 - Insulation resistance: 1000 M ohm
 - Contact resistance: 100 mill.ohm max
 - Operation temperature: -25℃ to +95℃
 - Product withstanding rff low soldering 260℃ for 10s

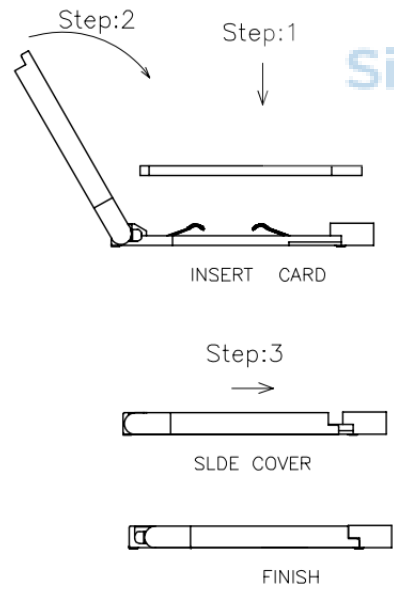
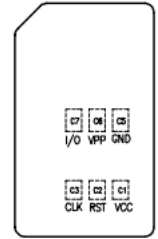
- C.Mechanical specieications:
- 3.1 Durability: 5000 cycles



芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

SIM 示意图

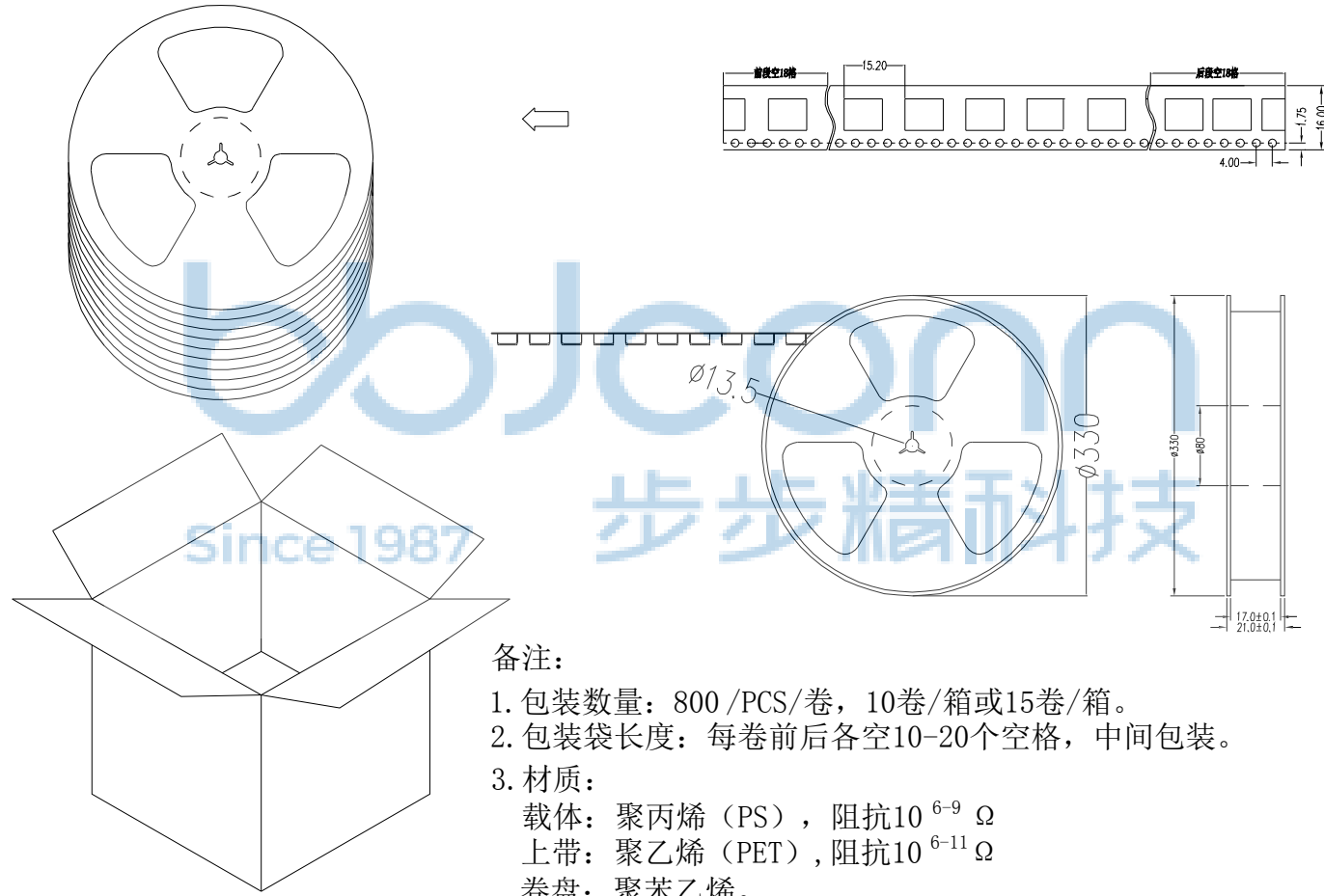


RECOMMENDED PCB PATTERN DIM.
TOLERANCE : ±0.05



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PDWG.NO: 0214-1	DR. SGF	APPD. JM_Zheng	CHKD. LYX

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



备注：
 1. 包装数量：800 /PCS/卷，10卷/箱或15卷/箱。
 2. 包装袋长度：每卷前后各空10-20个空格，中间包装。
 3. 材质：
 载体：聚丙烯（PS），阻抗 $10^{6-9} \Omega$
 上带：聚乙烯（PET），阻抗 $10^{6-11} \Omega$
 卷盘：聚苯乙烯。
 纸箱规格：345*345*23MM
 纸箱规格：345*345*35MM

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APPD.	JM_Zheng	PJ. NO.: CD.02.02-02-0004		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0214-1	DR.	SGF	SCALE: N/A	REV.: A0
				UNIT: mm	PAGE: 2/2